

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4707309	thermal\$4 heat\$4 infrared inferred infra adj red infer adj red inferred	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:21
L2	5182671	(dissipat\$4 conduct\$6 spread\$4 raiat\$4 sink\$4 emissiv\$6 dispers\$4 scatter\$4 diffus\$6 distribut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:21
L3	415402	epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:21
L4	1885286	resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:22
L5	2055	3 near2 1 near2 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:28
L6	5551	4 near2 1 near2 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:30
L7	3375733	ic integrated adj circuit chip die dice wafer substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:33
L8	4094326	back backside bottom underneath	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:34
L9	4206051	back backside bottom underneath underbody undersurface underside	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:34
L10	50151	scrib\$4 dicing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:36

L11	1616	(scrib\$4 align inscrib\$4) with dicing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:38
L12	267	(5 6) with 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 17:14
L13	2511	(scrib\$4 align\$4 inscrib\$4) with dicing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:38
L14	2511	(scrib\$4 align\$6 inscrib\$4) with dicing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:39
L15	5	12 and 14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:39
L16	168	(13) with 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 17:14
L17	4	12 and 16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:08
L18	544076	grind\$4 planariz\$4 polish\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:08
L19	553703	grind\$4 planariz\$4 polish\$4 cmp	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:13
L20	2	"20040113283".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:09

L21	1	20 and 19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:09
L22	2113790	grind\$4 planariz\$4 polish\$4 cmp thin\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:13
L23	2	20 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:27
L24	1	20 and (dicing separat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:28
L25	2	20 and (dic\$6 separat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:28
L26	2549	((438/113) or (438/114) or (438/126) or (438/127)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/01 18:32
S96	4707309	thermal\$4 heat\$4 infrared inferred infra adj red infer adj red infered	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:21
S97	8537	(dissipat\$4 conduct\$6 spread\$4 raiat\$4 sink\$4 emissiv\$6 dispers\$4 scatter\$4 diffus\$6 distribut\$4) near2 S96 near2 (liquid aqueous\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:21
S98	3375733	ic integrated adj circuit chip die dice wafer substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 12:59
S99	2827	S97 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 12:54

S10 0	50151	scrib\$4 dicing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:35
S10 1	90	S99 and S100	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 12:55
S10 2	79	S101 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:00
S10 3	3375733	ic integrated adj circuit chip die dice wafer substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 16:33
S10 4	79	S97 and S103 and S100 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:09
S10 5	6013261	dry dring dried solidif\$6 setting set seting harden\$4 indurat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:09
S10 6	79	S96 and S97 and S103 and S100 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:10
S10 7	79	S96 with S97 and S103 and S100 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:18
S10 8	0	S105 with S96 with S97 and S103 and S100 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:34
S10 9	6	S105 same S96 with S97 and S103 and S100 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:39